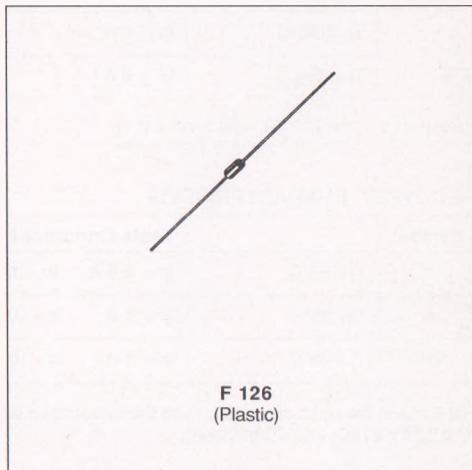


ULTRA FAST RECOVERY RECTIFIER DIODES

FEATURES

- SUITED FOR SMPS
- LOW LOSSES
- LOW FORWARD AND REVERSE RECOVERY TIME
- HIGH SURGE CURRENT CAPABILITY
- HIGH AVALANCHE ENERGY CAPABILITY



DESCRIPTION

Low cost single chip rectifier suited for switchmode power supply and high frequency DC to DC converters.

Packaged in F 126, this device is intended for use in low voltage, high frequency inverters, free wheeling and polarity protection applications.

ABSOLUTE RATINGS (limiting values)

| Symbol | Parameter | | Value | Unit |
|------------------------------------|--|--------------------------------------|--------------------------------|------|
| I _{F(AV)} | Average Forward Current | T _J = 60°C δ = 0.5 | 3 | A |
| I _{FSM} | Surge Non Repetitive Forward Current | T _p = 10 ms Sinusoidal | 30 | A |
| T _{stg} T _j | Storage and Junction Temperature Range | | - 65 to + 150 - 65 to + 150 | °C |

| Symbol | Parameter | STPR | | Unit |
|------------------|---------------------------------|------|-----|------|
| | | 310 | 320 | |
| V _{RRM} | Repetitive Peak Reverse Voltage | 100 | 200 | V |

THERMAL RESISTANCE

| Symbol | Parameter | Value | Unit |
|------------------------|----------------|-------|------|
| R _{th (j-L)*} | Junction-leads | 25 | °C/W |

* on infinite heatsink with L = 5mm lead length.

ELECTRICAL CHARACTERISTICS**STATIC CHARACTERISTICS**

| Symbol | Tests Conditions | | Min. | Typ. | Max. | Unit |
|--------|------------------------|-----------------------------------|------|------|------|------|
| IR * | T _j = 25°C | V _R = V _{RRM} | | | 10 | µA |
| | T _j = 100°C | | | | 0.5 | mA |
| VF ** | T _j = 125°C | I _F = 3 A | | | 0.99 | V |
| | T _j = 125°C | I _F = 6 A | | | 1.20 | |
| | T _j = 25°C | I _F = 6 A | | | 1.25 | |

Pulse test : * tp = 5 ms, duty cycle < 2 %

** tp = 380 µs, duty cycle < 2%

RECOVERY CHARACTERISTICS

| Symbol | Tests Conditions | | | Min. | Typ. | Max. | Unit | |
|-----------------|-----------------------|------------------------|---------------------|--|------|------|------|----|
| t _{rr} | T _j = 25°C | I _F = 0.5 A | I _R = 1A | I _{rr} = 0.25 A | | | 30 | ns |
| t _{fr} | T _j = 25°C | I _F = 1 A | tr = 10 ns | V _{FR} = 1.1 x V _F | | 20 | | ns |
| V _{FP} | T _j = 25°C | I _F = 1 A | tr = 10 ns | | | 3 | | V |

To evaluate the conduction losses use the following equation :

$$P = 0.78 \times I(F(AV)) + 0.070 I(F^2(RMS))$$

Fig.1 : Average forward power dissipation versus average forward current.

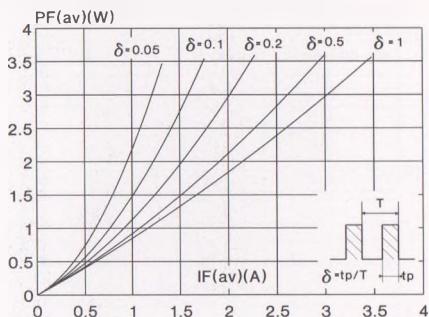


Fig.3 : Average current versus ambient temperature.
(duty cycle : 0.5)
* circuit board e (Cu) = 35 μ m, S (cu) = 12mm²
 $L_{(LEADS)}=20$ mm

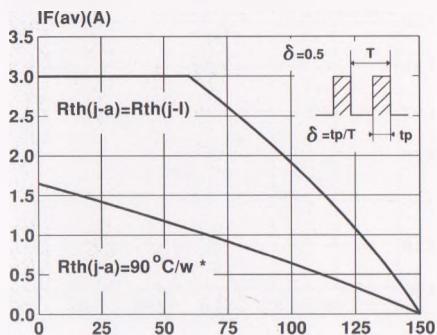


Fig.5 : Relative variation of thermal transient impedance junction to case versus pulse duration.

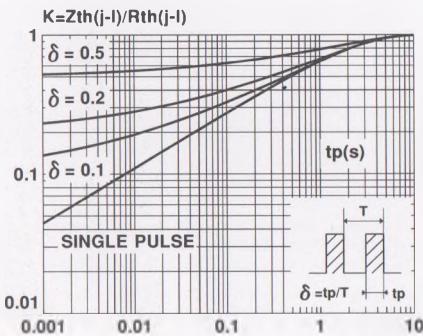


Fig.2 : Peak current versus form factor.

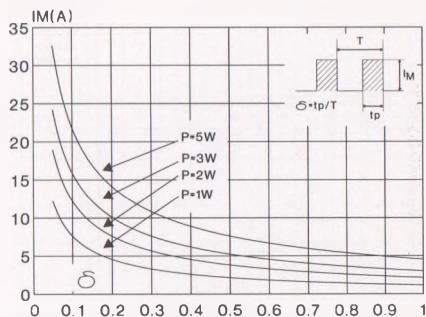


Fig.4 : Non repetitive surge peak forward current versus overload duration. (Maximum values)

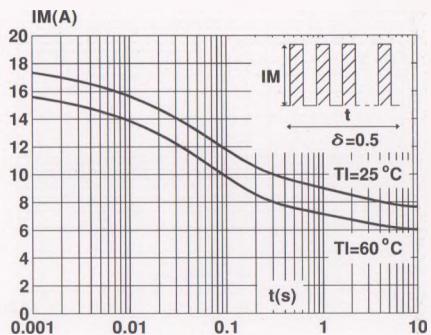


Fig.6 : Forward voltage drop versus forward current. (Maximum values)

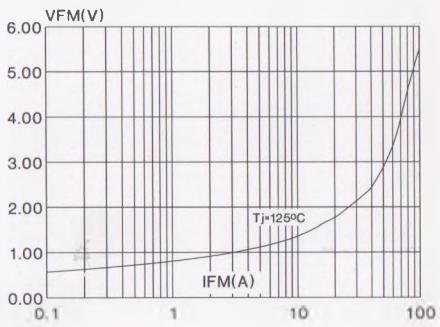


Fig.7 : Junction capacitance versus reverse voltage applied. (Typical values)

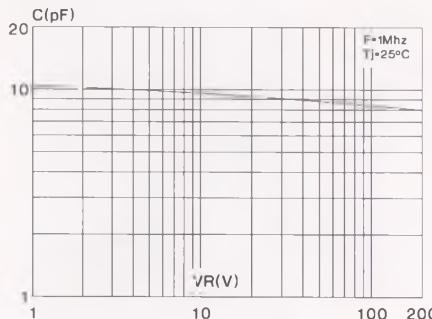


Fig.8 : Recovery charge versus dIF/dt.

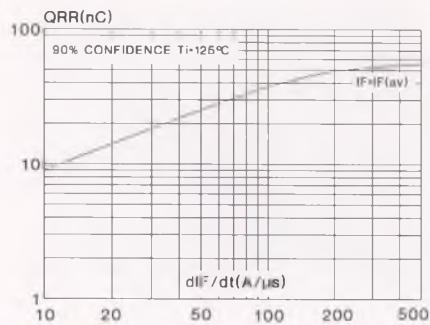


Fig.9 : Peak reverse current versus dIF/dt.

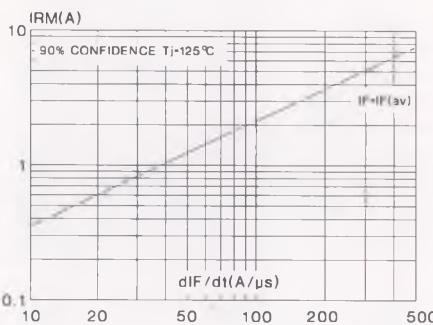


Fig.10 : Dynamic parameters versus junction temperature.

